



Attorney Docket No. 362-43 PCT/US/RCE

In re Application of: Yamamoto, et al.
Serial No.: 09/600,931
Confirmation No.: 2670
Filed: July 21, 2000
For: DAMASCENE INTERCONNECTION
AND SEMICONDUCTOR DEVICE

Commissioner For Patents
Washington, D.C. 20231

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Commissioner for Patents, Washington, D.C. 20231

on February 19, 2003

Signature: Maria Kising

Sir:

Transmitted herewith is an Amendment in the above-identified application.

- ☐ Small entity status of this application under 37 C.F.R. 1.9 and 1.27 has been established by a verified statement previously submitted.
- ☐ A verified statement to establish small entity status under 37 C.F.R. 1.9 and 1.27 is enclosed.
- ☒ No additional fee is required.

The fee has been calculated as shown below:

	(Col. 1)		(Col. 2)	(Col. 3)
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT EXTRA
TOTAL	* 16	MINUS	** 20	= 0
INDEP.	* 2	MINUS	*** 3	= 0

SMALL ENTITY

RATE	ADDL. FEE
x 9=	\$
x 40=	\$
x 135=	\$
TOTAL	\$ 0.00

OR

OTHER THAN A
SMALL ENTITY

RATE	ADDL. FEE
x 18=	\$
x 80=	\$
x 270=	\$
TOTAL	\$ 0.00

☐ FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIMS

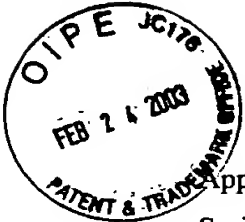
- ☐ Please charge my Deposit Account No. 502335 in the amount of \$_____. A duplicate copy of this sheet is attached.
- ☐ A check in the amount of \$_____ is attached.
- ☒ The Commissioner is hereby authorized to charge any fees or additional fees associated with this communication or credit any overpayment to Deposit Account No. 502335. A duplicate copy of this sheet is attached.
- ☒ Any filing fees under 37 C.F.R. 1.16 for the presentation of extra claims.
- ☒ Any patent application processing fees under 37 C.F.R. 1.17.

Respectfully submitted,

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants Yamamoto, et al.
Serial No.: 09/600,931
Confirmation No.: 2670
Filed: July 21, 2000
For: DAMASCENE
INTERCONNECTION AND
SEMICONDUCTOR
DEVICE

Examiner: Eugene Lee
Group Art Unit: 2815
Docket No.: 362-43 PCT/US
Dated: February 19, 2003

Commissioner for Patents
Washington, D.C. 20231

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Commissioner for Patents, Washington, D.C. 20231*

on February 19, 2003
Signature: Maria Rosing

REPLY TO OFFICE ACTION

Sir:

In response to the Office Action mailed September 19, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please add new Claims 17 and 18 as follows:

--17. A damascene interconnection as defined by claim 1, wherein the protrusion is formed as a plurality of island protrusions distributed within the pad trench, the plurality of island protrusions reducing the overall volume of the conductive film of the pad trench and increasing the electrical resistance of the conductive film of the pad trench, the further conductive film being formed below the insulating film and the plurality of island protrusions; and wherein the damascene interconnection further includes a plurality of contact holes formed within the pad trench, each contact hole of the plurality of contact holes being positioned near at least one island protrusion of the plurality of island protrusions, each contact hole of the plurality of contact holes being electrically connected between the conductive film of the pad trench and the further conductive film formed below the insulating film to define an electrical connection, the electrical connection between the conductive film

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